

PATENT  
81790.0227

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

Miki SASAKI, et al.

Serial No: 10/008,958

Filed: December 5, 2001

For: SEMICONDUCTOR DEVICE  
INCORPORATING A DICING TECHNIQUE  
FOR WAFER SEPARATION AND A  
METHOD FOR MANUFACTURING THE  
SAME (As Amended)

Art Unit: 2814

Examiner: Nathan W. Ha

I hereby certify that this correspondence is being facsimile transmitted to be received in the United States Patent and Trademark Office, Fax No. 703 746-4082 on February 4, 2003.

Sterlon R. Mason Reg. No. 41,179

Name

Signature

February 5, 2003

Date

REQUEST FOR EXTENSION OF TIME

Assistant Commissioner for Patents  
Washington, D.C. 20231

Dear Sir:

In accordance with 37 C.F.R. § 1.136, Applicants respectfully petition the Commissioner for a one-month extension of time extending from January 4, 2003 to February 4, 2003. The responsive papers are attached.

Please charge the fee of \$110.00 and any insufficiency or credit any overpayment to Deposit Account No. 50-1314.

Respectfully submitted,

HOGAN &amp; HARTSON, L.L.P.

Date: February 5, 2003

By:

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